

REMARKS

Claims 2-9 and 13-15 have been amended. Claims 1, 11 and 12 have been cancelled. Claim 16 and 17 have been added. Claims 2-9 and 13-17 remain for further consideration. No new matter has been added.

The objections and rejections shall be taken up in the order presented in the Official Action.

1. The drawings currently stand objected to for allegedly failing to show the delamination as recited in claim 12.

Claim 12 has been cancelled.

2. Claims 11 and 12 currently stand objected to for informalities.

Claims 11 and 12 have been cancelled.

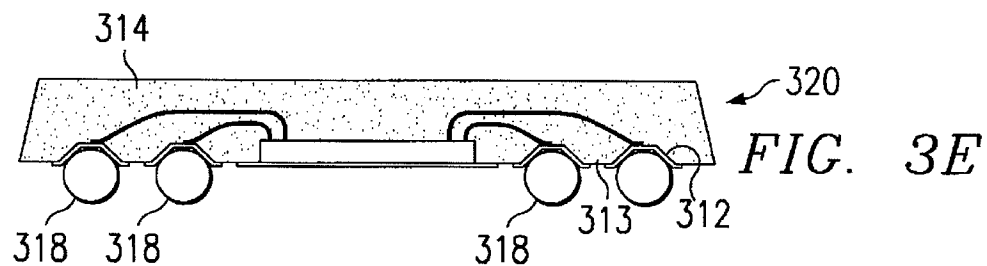
- 3-4. Claims 1-9 and 11-15 currently stand rejected for allegedly being anticipated by U.S. Patent 6,365,976 to Carter (hereinafter "Carter").

Claim 1 has been cancelled. Claim 16 has been added. It is respectfully submitted that the integrated circuit of claim 16 is patentable in view of Carter.

Claim 16 recites an integrated circuit, which includes a semiconductor die, a carrier device, bond wires and a package. The carrier device comprises *"a die paddle onto which the die is attached and a plurality of metallic leads each comprising an inner lead portion that extends to an outer lead portion, where a plurality of stamped pedestals are arranged on the carrier device exteriorly surrounding and adjacent to the die paddle."* (emphasis added, cl. 16).

A first bond wire extends from the die to a first of the plurality of stamped pedestals, and a second bond wire extends from the first of the plurality of stamped pedestals to an inner lead portion.

Carter discloses that bond wires extend directly from the die to the dimples 312. FIG. 3E is reproduced below in the interest of convenience.



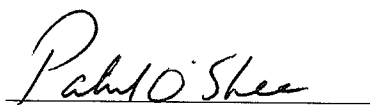
In contrast, as recited in claim 16, a first bond wire run from the die to the pedestal, and a second bond wire runs from the pedestal to a lead. In Carter, the bond wires run directly from the die to the lead 312. Hence, Carter is certainly incapable of anticipating claim 16. In addition, it is respectfully submitted that Carter is also incapable of rendering claim 16 obvious. There is no suggestion in Carter of a structure as set forth in claim 16, and there is nothing to indicate that a person of ordinary creativity would have considered the indirect bonding connection between the die and the I/O leads as recited in claim 16. As a result, it is respectfully submitted that claim 16 is patentable in view of Carter.

Claim 17 is patentable for at least the same reasons as claim 16.

For all the foregoing reasons, reconsideration and allowance of claims 2-9 and 13-17 is respectfully requested.

If a telephone interview could assist in the prosecution of this application, please call the undersigned attorney.

Respectfully submitted,

A handwritten signature in cursive script, reading "Patrick J. O'Shea", is written over a horizontal line.

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